



SOT1235

Plastic, single-ended surface-mounted package (LFPAK88; Power-SO8); 4 leads

13 June 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	LFPAK88
Package type industry code	LFPAK
Package style descriptive code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-6-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.15	-	6.3	6.45	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	1.65	-	1.75	1.85	mm
e	nominal pitch	-	-	2	-	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

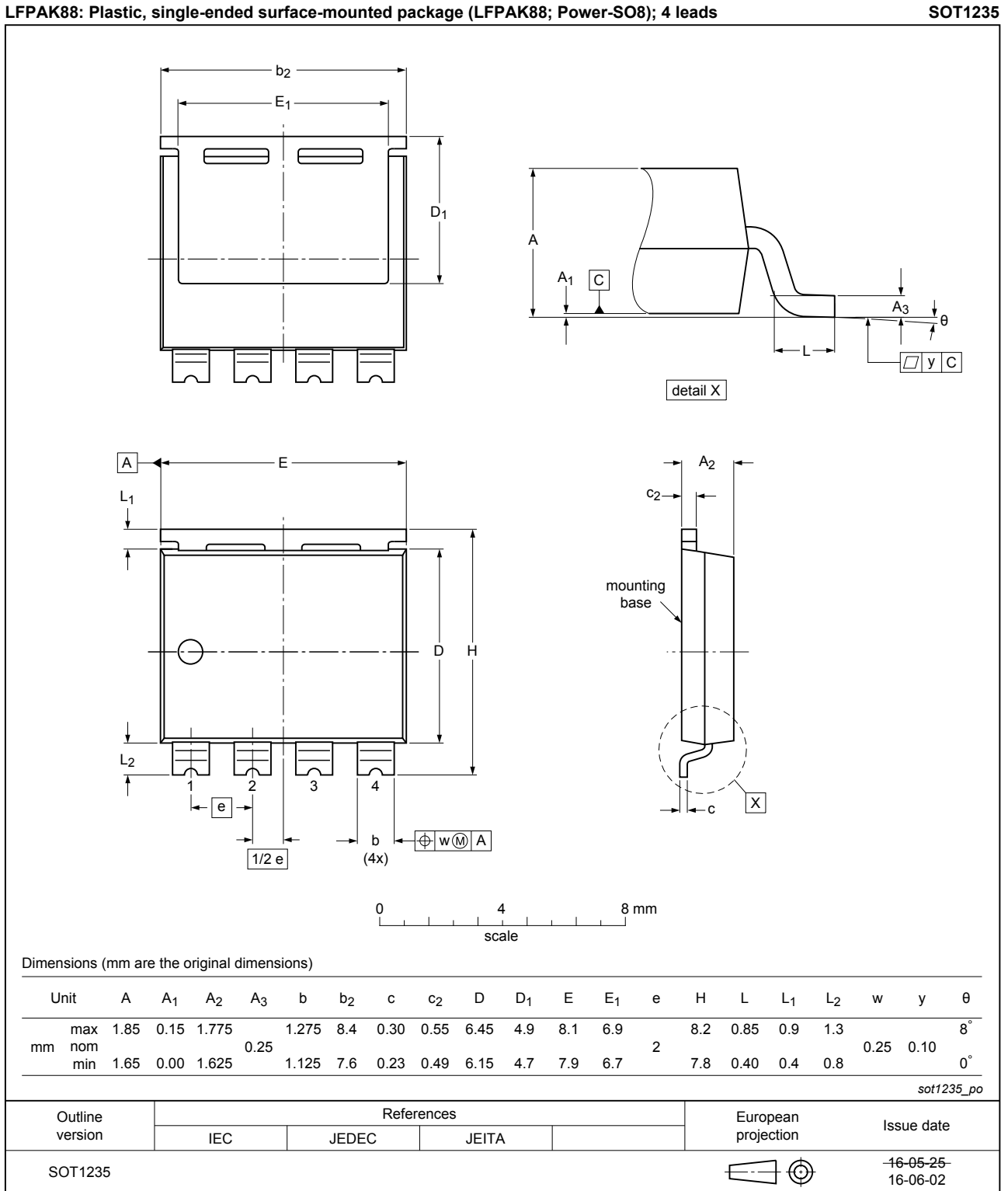


Fig. 1. Package outline LFAK (SOT1235)

3. Legal information

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